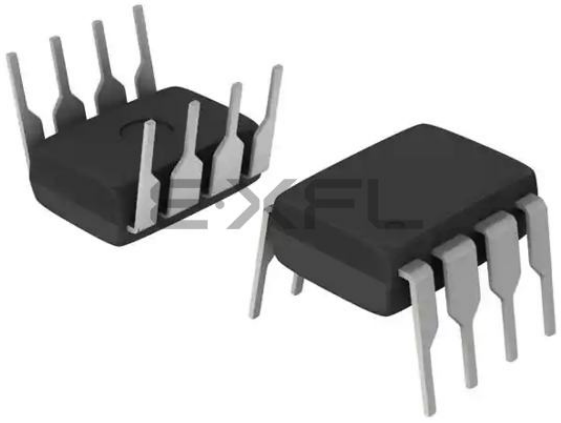

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12hv615-i-p

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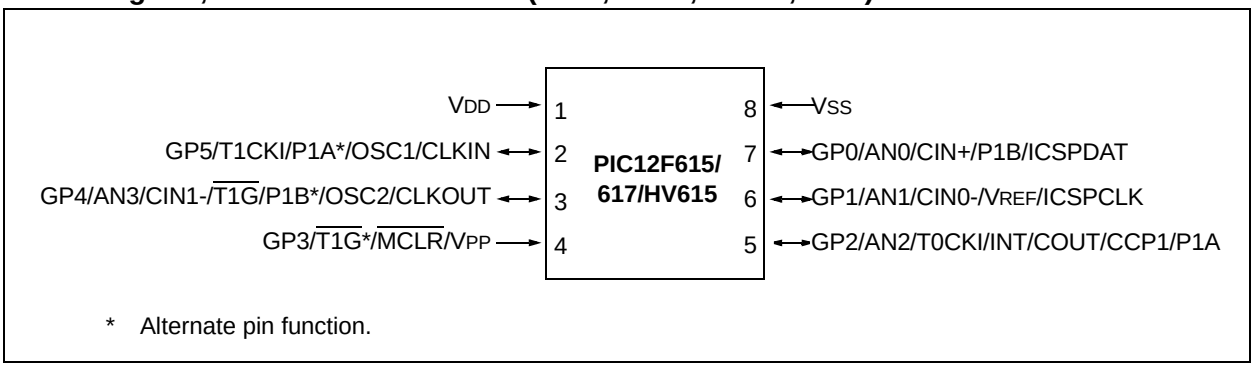
8-Pin Diagram, PIC12F615/617/HV615 (PDIP, SOIC, MSOP, DFN)



* Alternate pin function.

TABLE 2: PIC12F615/617/HV615 PIN SUMMARY (PDIP, SOIC, MSOP, DFN)

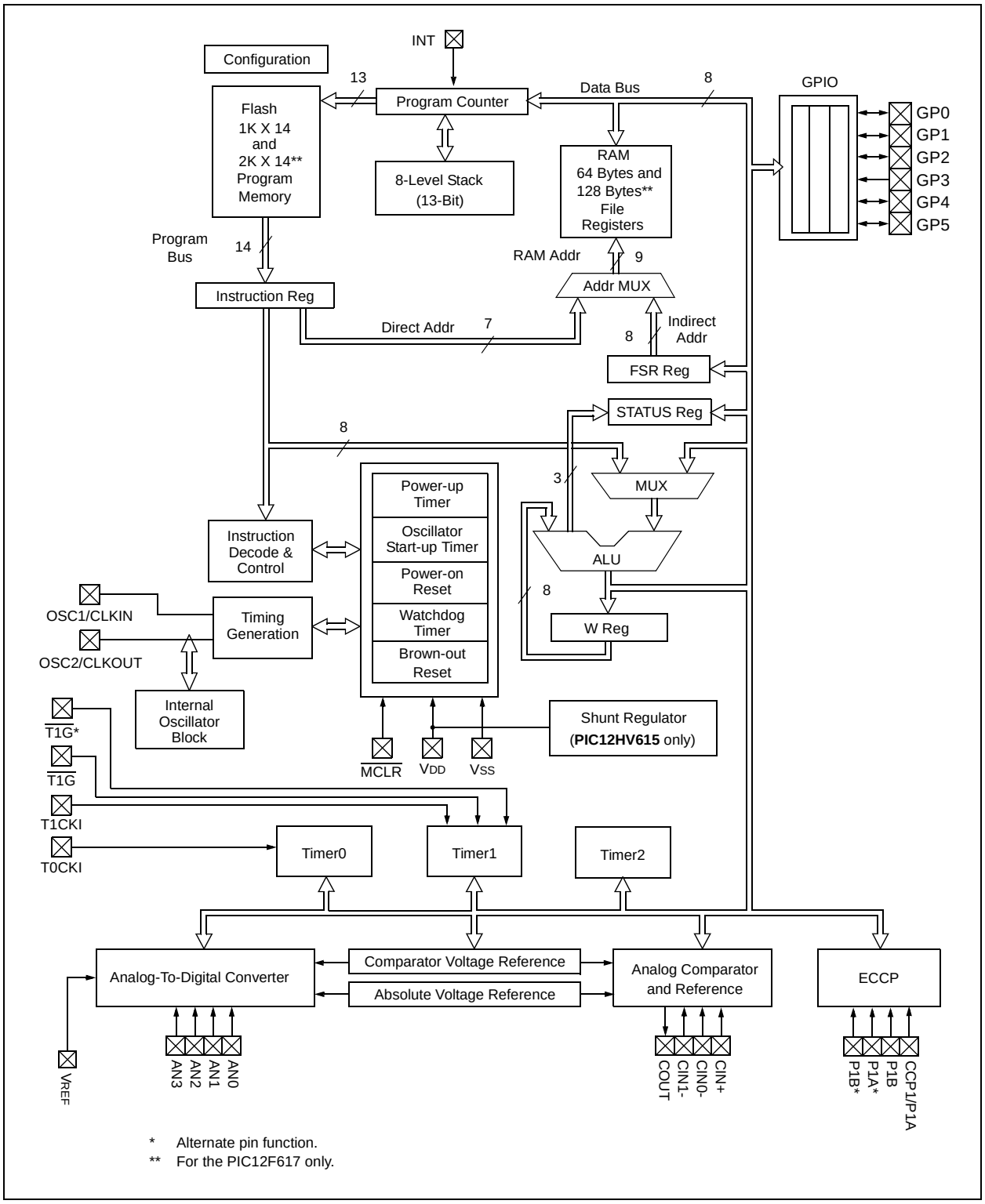
I/O	Pin	Analog	Comparators	Timer	CCP	Interrupts	Pull-ups	Basic
GP0	7	AN0	CIN+	—	P1B	IOC	Y	ICSPDAT
GP1	6	AN1	CIN0-	—	—	IOC	Y	ICSPCLK/VREF
GP2	5	AN2	COUT	T0CKI	CCP1/P1A	INT/IOC	Y	—
GP3(1)	4	—	—	T1G*	—	IOC	Y(2)	MCLR/VPP
GP4	3	AN3	CIN1-	T1G	P1B*	IOC	Y	OSC2/CLKOUT
GP5	2	—	—	T1CKI	P1A*	IOC	Y	OSC1/CLKIN
—	1	—	—	—	—	—	—	VDD
—	8	—	—	—	—	—	—	VSS

* Alternate pin function.

Note 1: Input only.

2: Only when pin is configured for external MCLR.

FIGURE 1-2: PIC12F615/617/HV615 BLOCK DIAGRAM



* Alternate pin function.
** For the PIC12F617 only.

TABLE 1-2: PIC12F615/617/HV615 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
GP0/AN0/CIN+/P1B/ICSPDAT	GP0	TTL	CMOS	General purpose I/O with prog. pull-up and interrupt-on-change
	AN0	AN	—	A/D Channel 0 input
	CIN+	AN	—	Comparator non-inverting input
	P1B	—	CMOS	PWM output
	ICSPDAT	ST	CMOS	Serial Programming Data I/O
GP1/AN1/CIN0-/VREF/ICSPCLK	GP1	TTL	CMOS	General purpose I/O with prog. pull-up and interrupt-on-change
	AN1	AN	—	A/D Channel 1 input
	CIN0-	AN	—	Comparator inverting input
	VREF	AN	—	External Voltage Reference for A/D
	ICSPCLK	ST	—	Serial Programming Clock
GP2/AN2/T0CKI/INT/COUT/CCP1/P1A	GP2	ST	CMOS	General purpose I/O with prog. pull-up and interrupt-on-change
	AN2	AN	—	A/D Channel 2 input
	T0CKI	ST	—	Timer0 clock input
	INT	ST	—	External Interrupt
	COUT	—	CMOS	Comparator output
	CCP1	ST	CMOS	Capture input/Compare input/PWM output
	P1A	—	CMOS	PWM output
GP3/$\overline{\text{T1G}}$*/$\overline{\text{MCLR}}$/VPP	GP3	TTL	—	General purpose input with interrupt-on-change
	$\overline{\text{T1G}}$*	ST	—	Timer1 gate (count enable), alternate pin
	$\overline{\text{MCLR}}$	ST	—	Master Clear w/internal pull-up
	VPP	HV	—	Programming voltage
GP4/AN3/CIN1-/$\overline{\text{T1G}}$/P1B*/OSC2/CLKOUT	GP4	TTL	CMOS	General purpose I/O with prog. pull-up and interrupt-on-change
	AN3	AN	—	A/D Channel 3 input
	CIN1-	AN	—	Comparator inverting input
	$\overline{\text{T1G}}$	ST	—	Timer1 gate (count enable)
	P1B*	—	CMOS	PWM output, alternate pin
	OSC2	—	XTAL	Crystal/Resonator
	CLKOUT	—	CMOS	FOSC/4 output
GP5/T1CKI/P1A*/OSC1/CLKIN	GP5	TTL	CMOS	General purpose I/O with prog. pull-up and interrupt-on-change
	T1CKI	ST	—	Timer1 clock input
	P1A*	—	CMOS	PWM output, alternate pin
	OSC1	XTAL	—	Crystal/Resonator
	CLKIN	ST	—	External clock input/RC oscillator connection
VDD	VDD	Power	—	Positive supply
VSS	VSS	Power	—	Ground reference

* Alternate pin function.

Legend: AN=Analog input or output CMOS=CMOS compatible input or output HV= High Voltage
ST=Schmitt Trigger input with CMOS levels TTL = TTL compatible input XTAL=Crystal

2.2.2.2 OPTION Register

The OPTION register is a readable and writable register, which contains various control bits to configure:

- Timer0/WDT prescaler
- External GP2/INT interrupt
- Timer0
- Weak pull-ups on GPIO

Note: To achieve a 1:1 prescaler assignment for Timer0, assign the prescaler to the WDT by setting PSA bit to '1' of the OPTION register. See **Section 6.1.3 "Software Programmable Prescaler"**.

REGISTER 2-2: OPTION_REG: OPTION REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{GPPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **$\overline{GPPU}$:** GPIO Pull-up Enable bit
1 = GPIO pull-ups are disabled
0 = GPIO pull-ups are enabled by individual PORT latch values

bit 6 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of GP2/INT pin
0 = Interrupt on falling edge of GP2/INT pin

bit 5 **T0CS:** Timer0 Clock Source Select bit
1 = Transition on GP2/T0CKI pin
0 = Internal instruction cycle clock (FOSC/4)

bit 4 **T0SE:** Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on GP2/T0CKI pin
0 = Increment on low-to-high transition on GP2/T0CKI pin

bit 3 **PSA:** Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS<2:0>:** Prescaler Rate Select bits

BIT VALUE	TIMER0 RATE	WDT RATE
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

3.4 Writing the Flash Program Memory

A word of the Flash program memory may only be written to if the word is in an unprotected segment of memory.

Flash program memory must be written in four-word blocks. See Figure 3-2 and Figure 3-3 for more details. A block consists of four words with sequential addresses, with a lower boundary defined by an address, where PMADRL<1:0> = 00. All block writes to program memory are done as 16-word erase by four-word write operations. The write operation is edge-aligned and cannot occur across boundaries.

To write program data, it must first be loaded into the buffer registers (see Figure 3-2). This is accomplished by first writing the destination address to PMADRL and PMADRH and then writing the data to PMDATL and PMDATH. After the address and data have been set up, then the following sequence of events must be executed:

1. Write 55h, then AAh, to PMCON2 (Flash programming sequence).
2. Set the WR control bit of the PMCON1 register.

All four buffer register locations should be written to with correct data. If less than four words are being written to in the block of four words, then a read from the program memory location(s) not being written to must be performed. This takes the data from the program location(s) not being written and loads it into the PMDATL and PMDATH registers. Then the sequence of events to transfer data to the buffer registers must be executed.

To transfer data from the buffer registers to the program memory, the PMADRL and PMADRH must point to the last location in the four-word block (PMADRL<1:0> = 11). Then the following sequence of events must be executed:

1. Write 55h, then AAh, to PMCON2 (Flash programming sequence).
2. Set control bit WR of the PMCON1 register to begin the write operation.

The user must follow the same specific sequence to initiate the write for each word in the program block, writing each program word in sequence (000, 001, 010, 011). When the write is performed on the last word (PMADRL<1:0> = 11), a block of sixteen words is automatically erased and the content of the four-word buffer registers are written into the program memory.

After the "BSF PMCON1,WR" instruction, the processor requires two cycles to set up the erase/write operation. The user must place two NOP instructions after the WR bit is set. Since data is being written to buffer registers, the writing of the first three words of the block appears to occur immediately. The processor will halt internal operations for the typical 4 ms, only during the cycle in which the erase takes place (i.e., the last word of the sixteen-word block erase). This is not Sleep mode as the clocks and peripherals will continue to run. After the four-word write cycle, the processor will resume operation with the third instruction after the PMCON1 write instruction. The above sequence must be repeated for the higher 12 words.

3.5 Protection Against Spurious Write

There are conditions when the device should not write to the program memory. To protect against spurious writes, various mechanisms have been built in. On power-up, WREN is cleared. Also, the Power-up Timer (64 ms duration) prevents program memory writes.

The write initiate sequence and the WREN bit help prevent an accidental write during brown-out, power glitch or software malfunction.

3.6 Operation During Code-Protect

When the device is code-protected, the CPU is able to read and write unscrambled data to the program memory. The test mode access is disabled.

3.7 Operation During Write Protect

When the program memory is write-protected, the CPU can read and execute from the program memory. The portions of program memory that are write protected can be modified by the CPU using the PMCON registers, but the protected program memory cannot be modified using ICSP mode.

4.2 Clock Source Modes

Clock Source modes can be classified as external or internal.

- External Clock modes rely on external circuitry for the clock source. Examples are: Oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.
- Internal clock sources are contained internally within the Oscillator module. The Oscillator module has two selectable clock frequencies: 4 MHz and 8 MHz

The system clock can be selected between external or internal clock sources via the FOSC<2:0> bits of the Configuration Word register.

4.3 External Clock Modes

4.3.1 OSCILLATOR START-UP TIMER (OST)

If the Oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the Oscillator module. When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 4-1.

TABLE 4-1: OSCILLATOR DELAY EXAMPLES

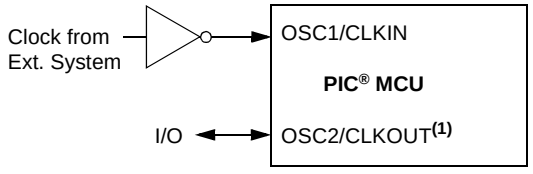
Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	INTOSC	125 kHz to 8 MHz	Oscillator Warm-Up Delay (TWARM)
Sleep/POR	EC, RC	DC – 20 MHz	2 instruction cycles
Sleep/POR	LP, XT, HS	32 kHz to 20 MHz	1024 Clock Cycles (OST)

4.3.2 EC MODE

The External Clock (EC) mode allows an externally generated logic level as the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input and the OSC2 is available for general purpose I/O. Figure 4-2 shows the pin connections for EC mode.

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 4-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Alternate pin functions are listed in the **Section 1.0 "Device Overview"**.

5.2.4 PIN DESCRIPTIONS AND DIAGRAMS

Each GPIO pin is multiplexed with other functions. The pins and their combined functions are briefly described here. For specific information about individual functions such as the Comparator or the ADC, refer to the appropriate section in this data sheet.

5.2.4.1 GP0/AN0(1)/CIN+/P1B(1)/ICSPDAT

Figure 5-1 shows the diagram for this pin. The GP0 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC(1)
- an analog non-inverting input to the comparator
- a PWM output(1)
- In-Circuit Serial Programming data

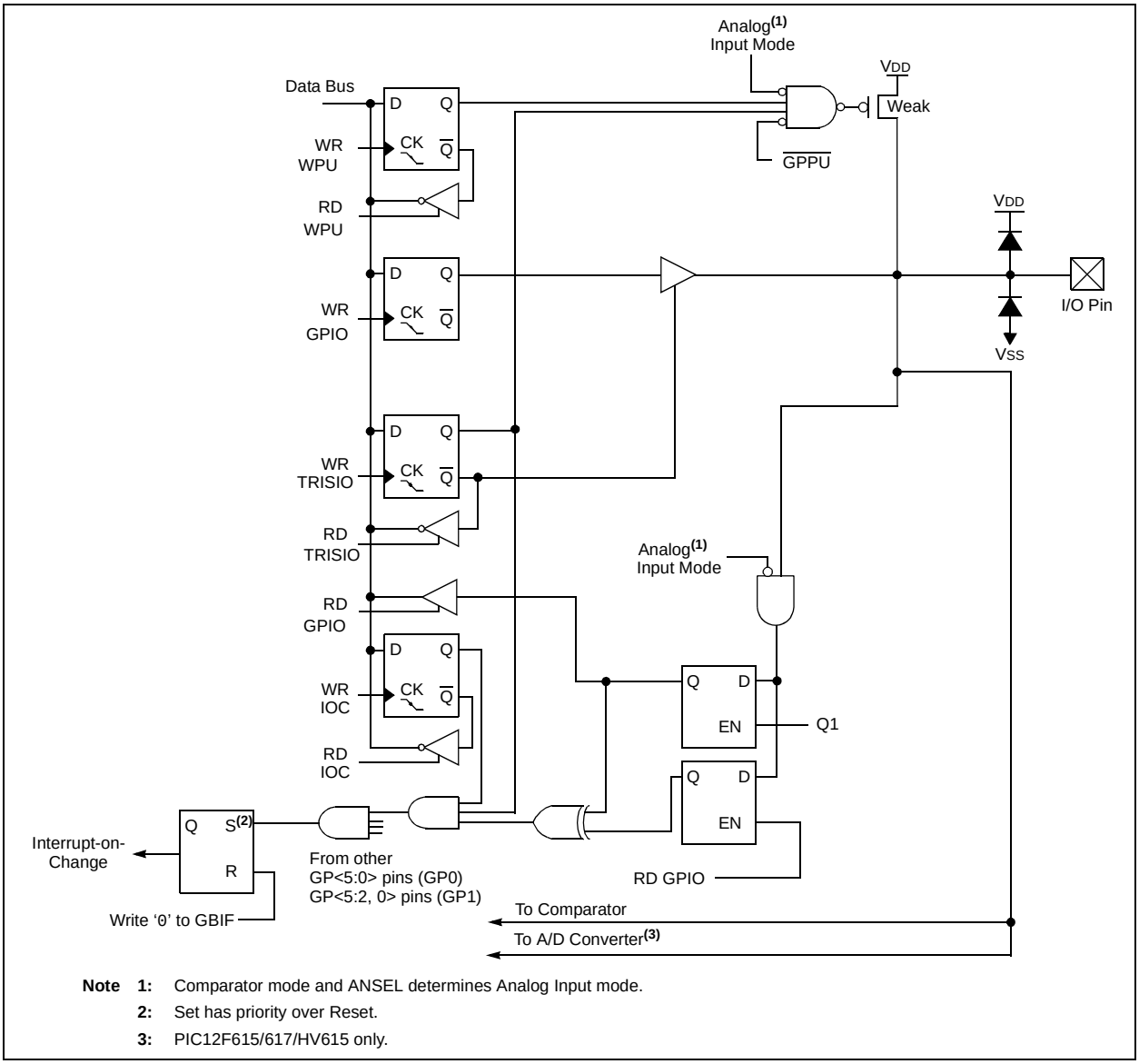
5.2.4.2 GP1/AN1(1)/CIN0-/VREF(1)/ICSPCLK

Figure 5-1 shows the diagram for this pin. The GP1 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC(1)
- an analog inverting input to the comparator
- a voltage reference input for the ADC(1)
- In-Circuit Serial Programming clock

Note 1: PIC12F615/617/HV615 only.

FIGURE 5-1: BLOCK DIAGRAM OF GP<1:0>



Note 1: Comparator mode and ANSEL determines Analog Input mode.
2: Set has priority over Reset.
3: PIC12F615/617/HV615 only.

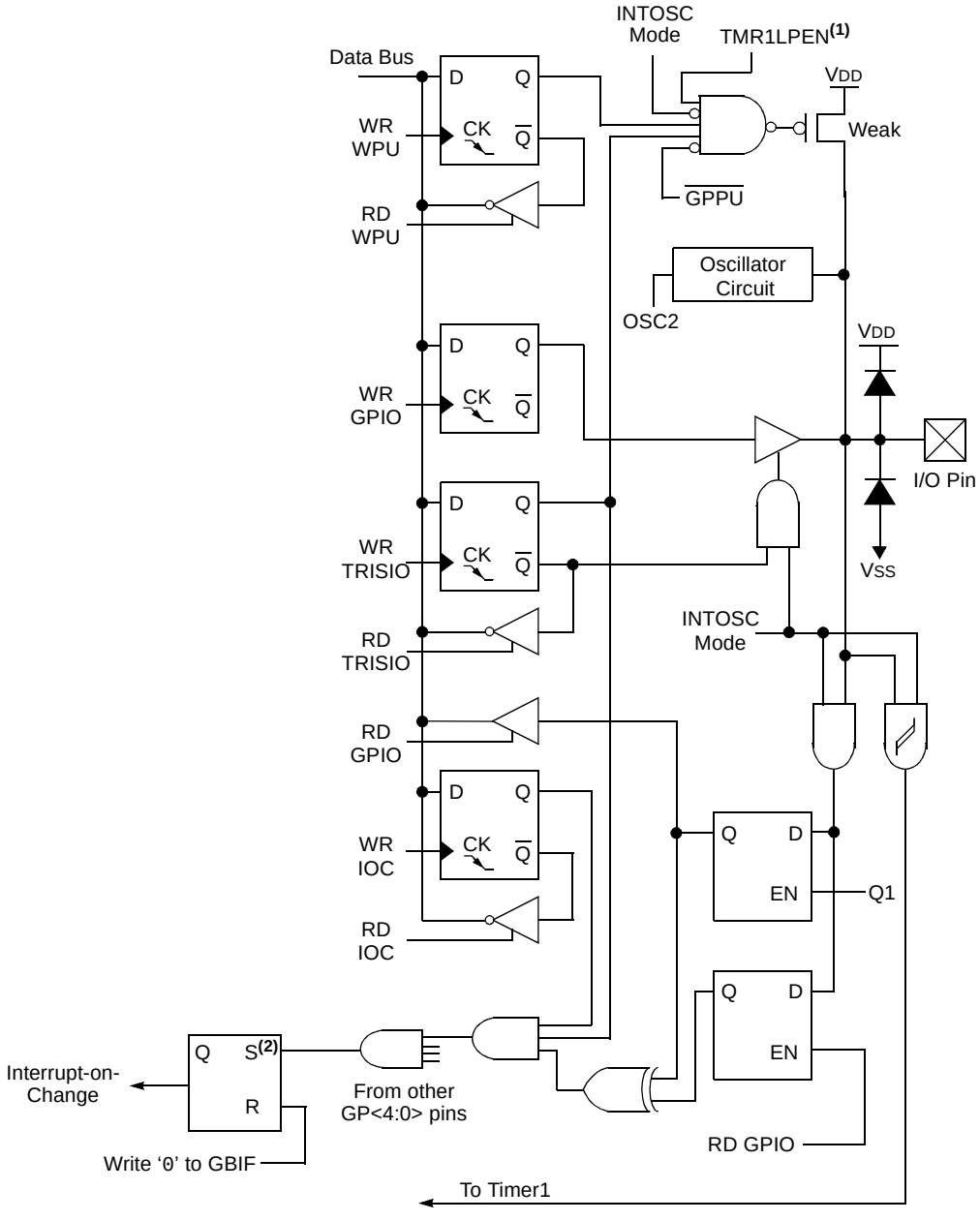
5.2.4.6 GP5/T1CKI/P1A(1, 2)/OSC1/CLKIN

Figure 5-5 shows the diagram for this pin. The GP5 pin is configurable to function as one of the following:

- a general purpose I/O
- a Timer1 clock input
- PWM output, alternate pin(1, 2)
- a crystal/resonator connection
- a clock input

Note 1: Alternate pin function.
2: PIC12F615/617/HV615 only.

FIGURE 5-5: BLOCK DIAGRAM OF GP5



Note 1: Timer1 LP Oscillator enabled.
2: Set has priority over Reset.

REGISTER 8-1: T2CON: TIMER 2 CONTROL REGISTER

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **TOUTPS<3:0>:** Timer2 Output Postscaler Select bits
0000 =1:1 Postscaler
0001 =1:2 Postscaler
0010 =1:3 Postscaler
0011 =1:4 Postscaler
0100 =1:5 Postscaler
0101 =1:6 Postscaler
0110 =1:7 Postscaler
0111 =1:8 Postscaler
1000 =1:9 Postscaler
1001 =1:10 Postscaler
1010 =1:11 Postscaler
1011 =1:12 Postscaler
1100 =1:13 Postscaler
1101 =1:14 Postscaler
1110 =1:15 Postscaler
1111 =1:16 Postscaler

bit 2 **TMR2ON:** Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS<1:0>:** Timer2 Clock Prescale Select bits
00 =Prescaler is 1
01 =Prescaler is 4
1x =Prescaler is 16

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER2

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 0000
PIE1	—	ADIE(1)	CCP1IE(1)	—	CMIE	—	TMR2IE(1)	TMR1IE	-00- 0-00	-00- 0-00
PIR1	—	ADIF(1)	CCP1IF(1)	—	CMIF	—	TMR2IF(1)	TMR1IF	-00- 0-00	-00- 0-00
PR2(1)	Timer2 Module Period Register								1111 1111	1111 1111
TMR2(1)	Holding Register for the 8-bit TMR2 Register								0000 0000	0000 0000
T2CON(1)	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for Timer2 module.
Note 1: For PIC12F615/617/HV615 only.

9.5 Comparator Interrupt Operation

The comparator interrupt flag can be set whenever there is a change in the output value of the comparator. Changes are recognized by means of a mismatch circuit which consists of two latches and an exclusive-or gate (see Figure 9-4 and Figure 9-5). One latch is updated with the comparator output level when the CMCON0 register is read. This latch retains the value until the next read of the CMCON0 register or the occurrence of a Reset. The other latch of the mismatch circuit is updated on every Q1 system clock. A mismatch condition will occur when a comparator output change is clocked through the second latch on the Q1 clock cycle. At this point the two mismatch latches have opposite output levels which is detected by the exclusive-or gate and fed to the interrupt circuitry. The mismatch condition persists until either the CMCON0 register is read or the comparator output returns to the previous state.

Note 1:	A write operation to the CMCON0 register will also clear the mismatch condition because all writes include a read operation at the beginning of the write cycle.
2:	Comparator interrupts will operate correctly regardless of the state of CMOE.

The comparator interrupt is set by the mismatch edge and not the mismatch level. This means that the interrupt flag can be reset without the additional step of reading or writing the CMCON0 register to clear the mismatch registers. When the mismatch registers are cleared, an interrupt will occur upon the comparator's return to the previous state, otherwise no interrupt will be generated.

Software will need to maintain information about the status of the comparator output, as read from the CMCON1 register, to determine the actual change that has occurred.

The CMIF bit of the PIR1 register is the Comparator Interrupt flag. This bit must be reset in software by clearing it to '0'. Since it is also possible to write a '1' to this register, an interrupt can be generated.

The CMIE bit of the PIE1 register and the PEIE and GIE bits of the INTCON register must all be set to enable comparator interrupts. If any of these bits are cleared, the interrupt is not enabled, although the CMIF bit of the PIR1 register will still be set if an interrupt condition occurs.

FIGURE 9-4: COMPARATOR INTERRUPT TIMING W/O CMCON0 READ

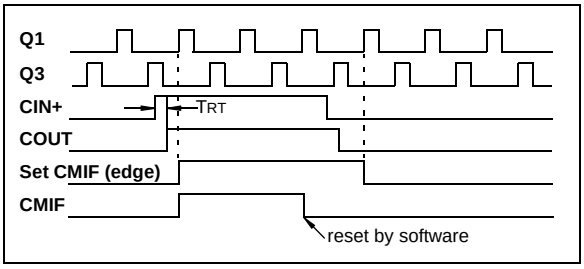
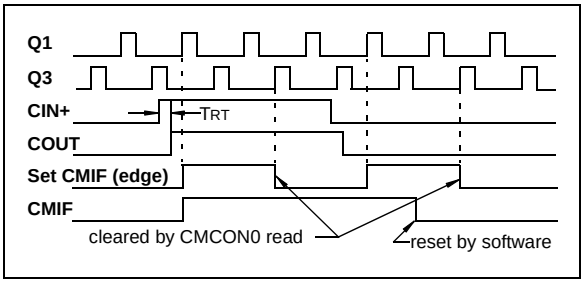


FIGURE 9-5: COMPARATOR INTERRUPT TIMING WITH CMCON0 READ



Note 1:	If a change in the CMCON0 register (COUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF of the PIR1 register interrupt flag may not get set.
2:	When a comparator is first enabled, bias circuitry in the comparator module may cause an invalid output from the comparator until the bias circuitry is stable. Allow about 1 μs for bias settling then clear the mismatch condition and interrupt flags before enabling comparator interrupts.

TABLE 10-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES (VDD ≥ 3.0V)

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})			
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
F_{OSC}/2	000	100 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
F_{OSC}/4	100	200 ns(2)	500 ns(2)	1.0 μs(2)	4.0 μs
F_{OSC}/8	001	400 ns(2)	1.0 μs(2)	2.0 μs	8.0 μs(3)
F_{OSC}/16	101	800 ns(2)	2.0 μs	4.0 μs	16.0 μs(3)
F_{OSC}/32	010	1.6 μs	4.0 μs	8.0 μs(3)	32.0 μs(3)
F_{OSC}/64	110	3.2 μs	8.0 μs(3)	16.0 μs(3)	64.0 μs(3)
F_{RC}	x11	2-6 μs(1,4)	2-6 μs(1,4)	2-6 μs(1,4)	2-6 μs(1,4)

Legend: Shaded cells are outside of recommended range.

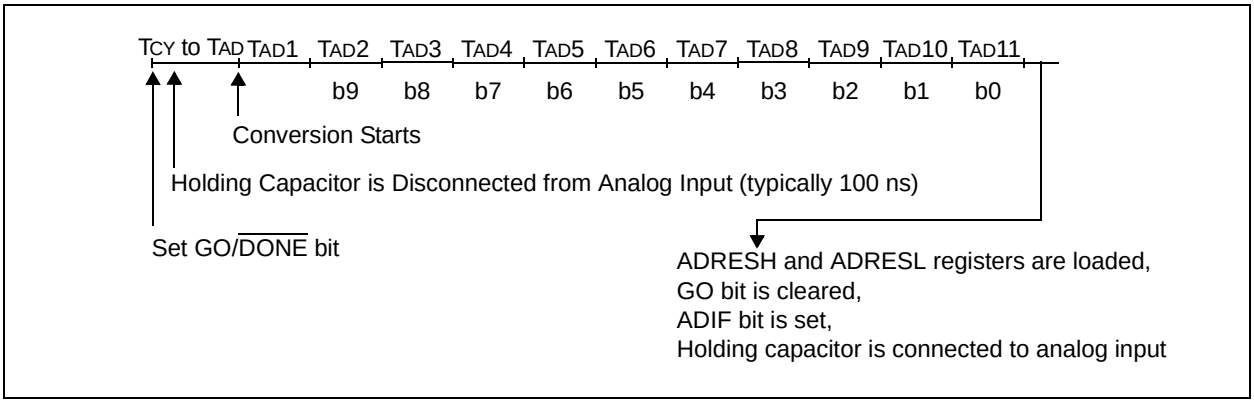
Note 1: The F_{RC} source has a typical T_{AD} time of 4 μs for V_{DD} > 3.0V.

2: These values violate the minimum required T_{AD} time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the F_{RC} clock source is only recommended if the conversion will be performed during Sleep.

FIGURE 10-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



10.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC interrupt flag is the ADIF bit in the PIR1 register. The ADC interrupt enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the global interrupt must be disabled. If the global interrupt is enabled, execution will switch to the Interrupt Service Routine.

Please see **Section 10.1.5 "Interrupts"** for more information.

11.2 Compare Mode

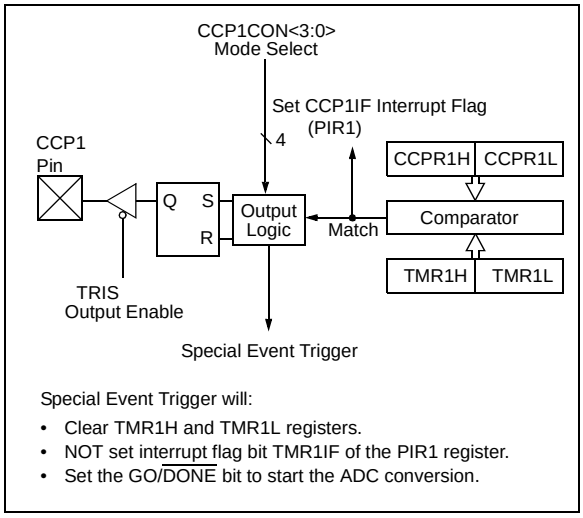
In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the CCP1 module may:

- Toggle the CCP1 output.
- Set the CCP1 output.
- Clear the CCP1 output.
- Generate a Special Event Trigger.
- Generate a Software Interrupt.

The action on the pin is based on the value of the CCP1M<3:0> control bits of the CCP1CON register.

All Compare modes can generate an interrupt.

FIGURE 11-2: COMPARE MODE OPERATION BLOCK DIAGRAM



11.2.1 CCP1 PIN CONFIGURATION

The user must configure the CCP1 pin as an output by clearing the associated TRIS bit.

Note:	Clearing the CCP1CON register will force the CCP1 compare output latch to the default low level. This is not the PORT I/O data latch.

11.2.2 TIMER1 MODE SELECTION

In Compare mode, Timer1 must be running in either Timer mode or Synchronized Counter mode. The compare operation may not work in Asynchronous Counter mode.

11.2.3 SOFTWARE INTERRUPT MODE

When Generate Software Interrupt mode is chosen (CCP1M<3:0> = 1010), the CCP1 module does not assert control of the CCP1 pin (see the CCP1CON register).

11.2.4 SPECIAL EVENT TRIGGER

When Special Event Trigger mode is chosen (CCP1M<3:0> = 1011), the CCP1 module does the following:

- Resets Timer1
- Starts an ADC conversion if ADC is enabled

The CCP1 module does not assert control of the CCP1 pin in this mode (see the CCP1CON register).

The Special Event Trigger output of the CCP occurs immediately upon a match between the TMR1H, TMR1L register pair and the CCPR1H, CCPR1L register pair. The TMR1H, TMR1L register pair is not reset until the next rising edge of the Timer1 clock. This allows the CCPR1H, CCPR1L register pair to effectively provide a 16-bit programmable period register for Timer1.

Note 1:	The Special Event Trigger from the CCP module does not set interrupt flag bit TMRxIF of the PIR1 register.
2:	Removing the match condition by changing the contents of the CCPR1H and CCPR1L register pair, between the clock edge that generates the Special Event Trigger and the clock edge that generates the Timer1 Reset, will preclude the Reset from occurring.

12.3.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in Reset until V_{DD} has reached a high enough level for proper operation. To take advantage of the POR, simply connect the $\overline{MCLR}$ pin through a resistor to V_{DD}. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for V_{DD} is required. See **Section 16.0 "Electrical Specifications"** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until V_{DD} reaches V_{BOR} (see **Section 12.3.4 "Brown-out Reset (BOR)"**).

Note:	The POR circuit does not produce an internal Reset when V_{DD} declines. To re-enable the POR, V_{DD} must reach Vss for a minimum of 100 µs.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure proper operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

12.3.2 $\overline{MCLR}$

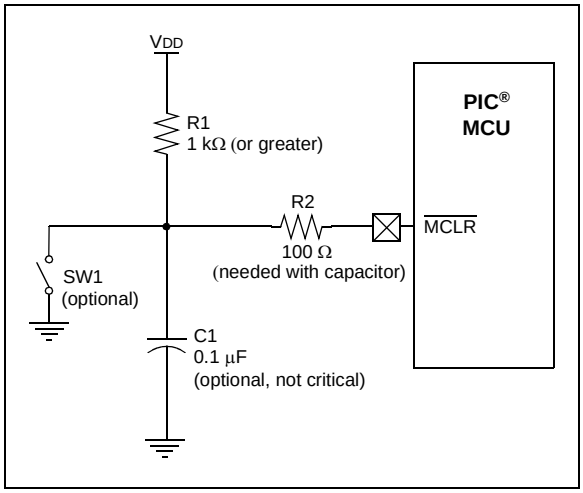
PIC12F609/615/617/12HV609/615 has a noise filter in the $\overline{MCLR}$ Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{MCLR}$ pin low.

Voltages applied to the $\overline{MCLR}$ pin that exceed its specification can result in both $\overline{MCLR}$ Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the $\overline{MCLR}$ pin no longer be tied directly to V_{DD}. The use of an RC network, as shown in Figure 12-2, is suggested.

An internal $\overline{MCLR}$ option is enabled by clearing the MCLRE bit in the Configuration Word register. When MCLRE = 0, the Reset signal to the chip is generated internally. When the MCLRE = 1, the GP3/$\overline{MCLR}$ pin becomes an external Reset input. In this mode, the GP3/$\overline{MCLR}$ pin has a weak pull-up to V_{DD}.

FIGURE 12-2: RECOMMENDED $\overline{MCLR}$ CIRCUIT



12.3.3 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from an internal RC oscillator. For more information, see **Section 4.4 "Internal Clock Modes"**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the V_{DD} to rise to an acceptable level. A Configuration bit, $\overline{PWRTE}$, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip due to:

- V_{DD} variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 16.0 "Electrical Specifications"**).

Note:	Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin, rather than pulling this pin directly to V_{SS}.

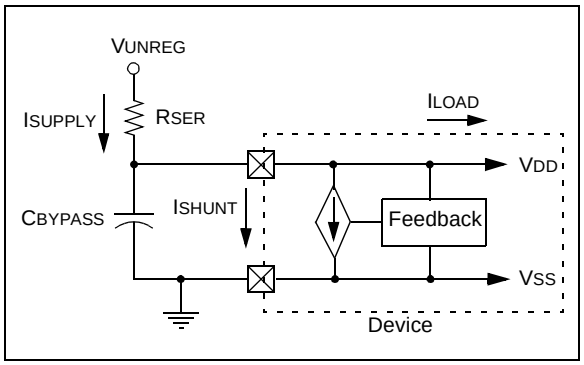
13.0 VOLTAGE REGULATOR

The PIC12HV609/HV615 devices include a permanent internal 5 volt (nominal) shunt regulator in parallel with the VDD pin. This eliminates the need for an external voltage regulator in systems sourced by an unregulated supply. All external devices connected directly to the VDD pin will share the regulated supply voltage and contribute to the total VDD supply current (ILOAD).

13.1 Regulator Operation

A shunt regulator generates a specific supply voltage by creating a voltage drop across a pass resistor RSER. The voltage at the VDD pin of the microcontroller is monitored and compared to an internal voltage reference. The current through the resistor is then adjusted, based on the result of the comparison, to produce a voltage drop equal to the difference between the supply voltage VUNREG and the VDD of the microcontroller. See Figure 13-1 for voltage regulator schematic.

FIGURE 13-1: VOLTAGE REGULATOR



An external current limiting resistor, RSER, located between the unregulated supply, VUNREG, and the VDD pin, drops the difference in voltage between VUNREG and VDD. RSER must be between RMAX and RMIN as defined by Equation 13-1.

EQUATION 13-1: RSER LIMITING RESISTOR

$$R_{MAX} = \frac{(VU_{MIN} - 5V)}{1.05 \bullet (4\ mA + I_{LOAD})}$$

$$R_{MIN} = \frac{(VU_{MAX} - 5V)}{0.95 \bullet (50\ mA)}$$

Where:

RMAX = maximum value of RSER (ohms)

RMIN = minimum value of RSER (ohms)

VUMIN = minimum value of VUNREG

VUMAX = maximum value of VUNREG

VDD = regulated voltage (5V nominal)

ILOAD = maximum expected load current in mA including I/O pin currents and external circuits connected to VDD.

1.05 = compensation for +5% tolerance of RSER

0.95 = compensation for -5% tolerance of RSER

13.2 Regulator Considerations

The supply voltage VUNREG and load current are not constant. Therefore, the current range of the regulator is limited. Selecting a value for RSER must take these three factors into consideration.

Since the regulator uses the band gap voltage as the regulated voltage reference, this voltage reference is permanently enabled in the PIC12HV609/HV615 devices.

The shunt regulator will still consume current when below operating voltage range for the shunt regulator.

13.3 Design Considerations

For more information on using the shunt regulator and managing current load, see Application Note AN1035, "*Designing with HV Microcontrollers"* (DS01035).

TABLE 16-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym**	**Characteristic**	**Freq. Tolerance**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
OS06	TWARM	Internal Oscillator Switch when running(3)	—	—	—	2	TOSC	Slowest clock
OS07	INTOSC	Internal Calibrated INTOSC Frequency(2) (4MHz)	±1%	3.96	4.0	4.04	MHz	VDD = 3.5V, T_A = 25°C
			±2%	3.92	4.0	4.08	MHz	2.5V ≤ VDD ≤ 5.5V, 0°C ≤ TA ≤ +85°C
			±5%	3.80	4.0	4.2	MHz	2.0V ≤ VDD ≤ 5.5V, -40°C ≤ TA ≤ +85°C (Ind.), -40°C ≤ TA ≤ +125°C (Ext.)
OS08	INTOSC	Internal Calibrated INTOSC Frequency(2) (8MHz)	±1%	7.92	8.0	8.08	MHz	VDD = 3.5V, T_A = 25°C
			±2%	7.84	8.0	8.16	MHz	2.5V ≤ VDD ≤ 5.5V, 0°C ≤ TA ≤ +85°C
			±5%	7.60	8.0	8.40	MHz	2.0V ≤ VDD ≤ 5.5V, -40°C ≤ TA ≤ +85°C (Ind.), -40°C ≤ TA ≤ +125°C (Ext.)
OS10*	TIOSC ST	INTOSC Oscillator Wake-up from Sleep Start-up Time	—	5.5	12	24	µs	VDD = 2.0V, -40°C to +85°C
			—	3.5	7	14	µs	VDD = 3.0V, -40°C to +85°C
			—	3	6	11	µs	VDD = 5.0V, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: By design.

TABLE 16-12: PIC12F615/617/HV615 A/D CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD130*	TAD	A/D Clock Period	1.6	—	9.0	µs	TOSC-based, VREF ≥ 3.0V
			3.0	—	9.0	µs	TOSC-based, VREF full range(3)
		A/D Internal RC Oscillator Period					ADCS<1:0> = 11 (ADRC mode)
			3.0	6.0	9.0	µs	At VDD = 2.5V
			1.6	4.0	6.0	µs	At VDD = 5.0V
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to new data in A/D Result register
AD132*	TACQ	Acquisition Time		11.5	—	µs	
AD133*	TAMP	Amplifier Settling Time	—	—	5	µs	
AD134	TGO	Q4 to A/D Clock Start	—	TOSC/2	—	—	
			—	TOSC/2 + TCY	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

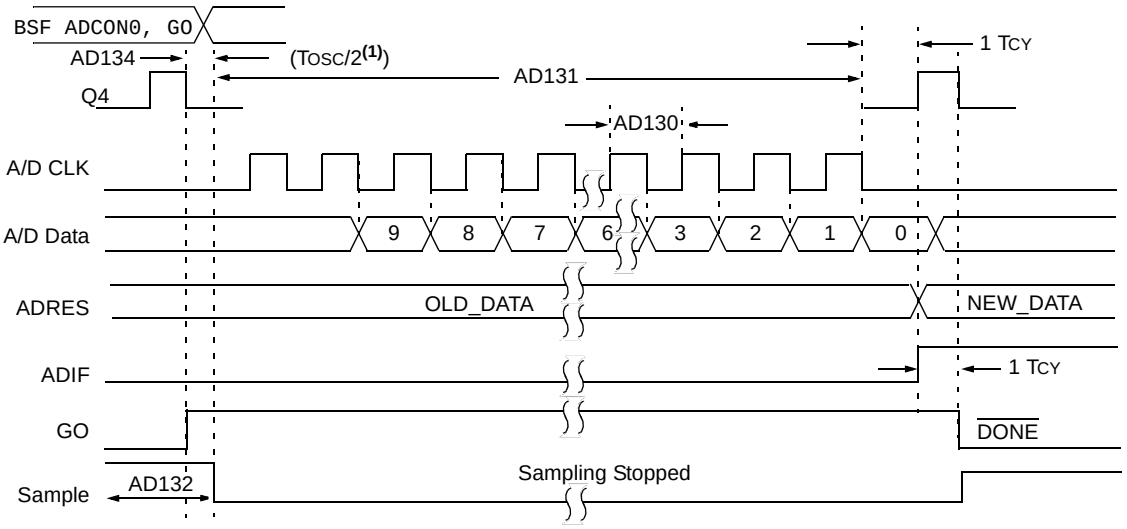
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRESH and ADRESL registers may be read on the following TCY cycle.

2: See **Section 10.3 "A/D Acquisition Requirements"** for minimum conditions.

3: Full range for PIC12HV609/HV615 powered by the shunt regulator is the 5V regulated voltage.

FIGURE 16-10: PIC12F615/617/HV615 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 17-39: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE

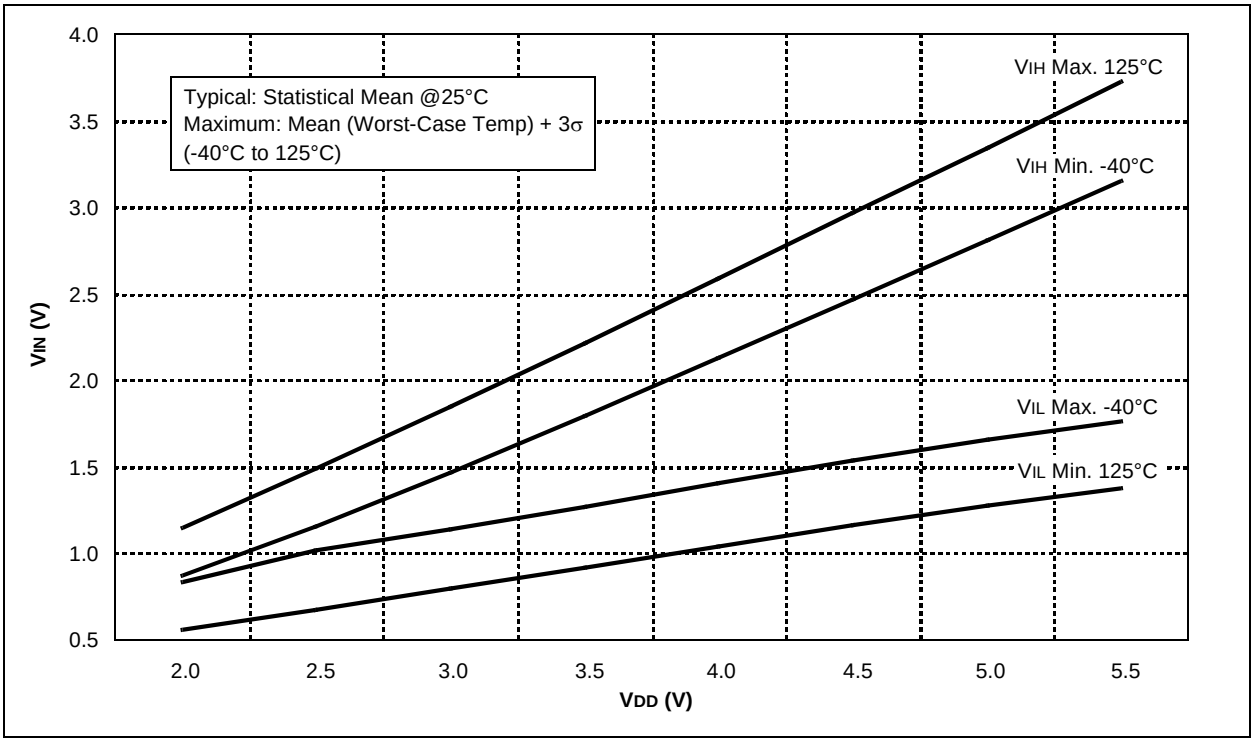
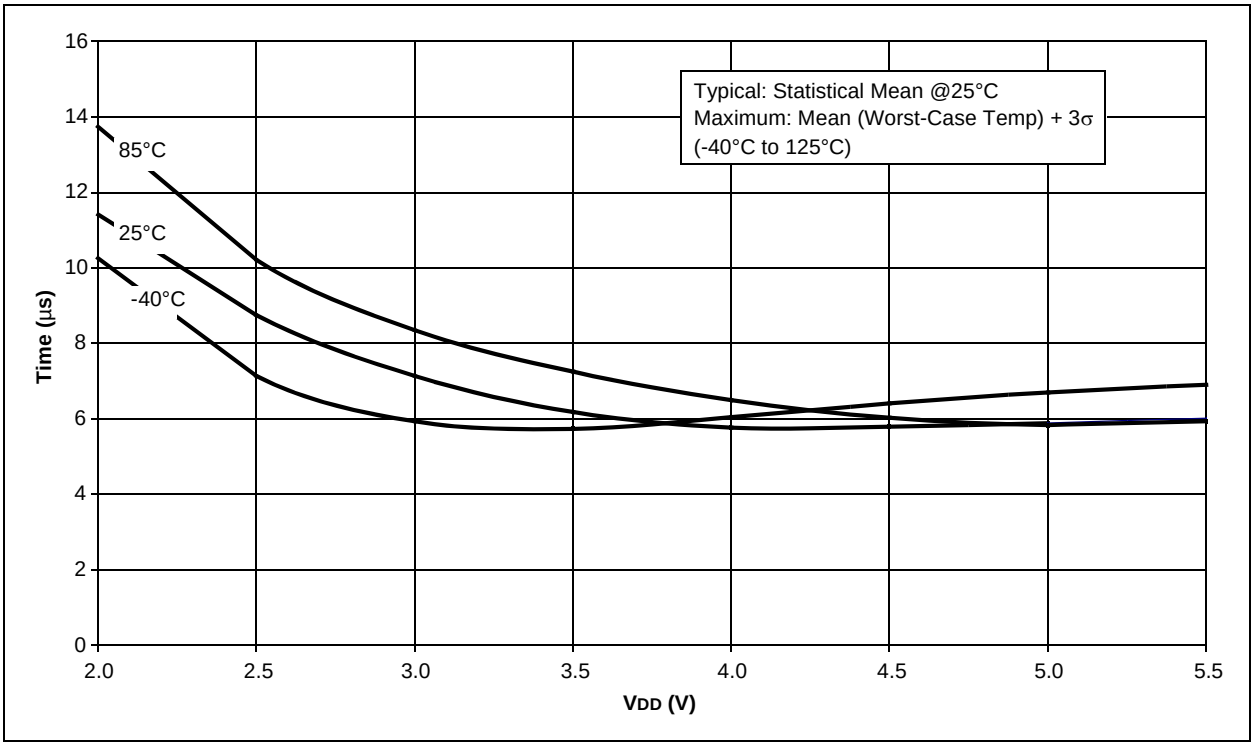
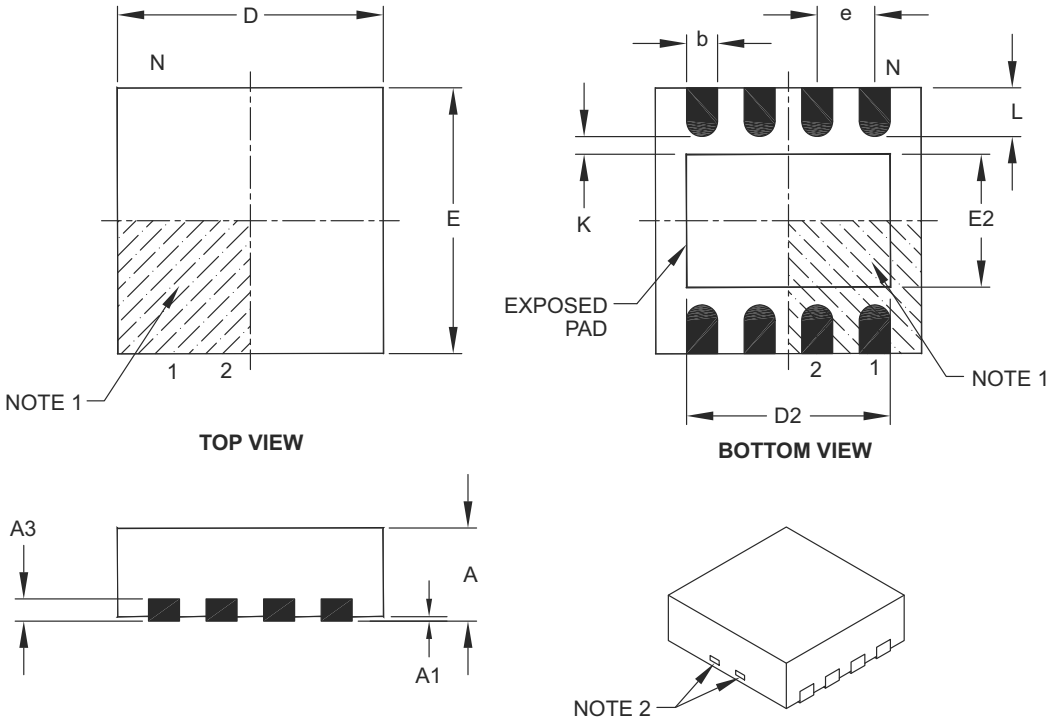


FIGURE 17-40: TYPICAL HFINTOSC START-UP TIMES vs. VDD OVER TEMPERATURE



8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.80 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Length	D		4.00 BSC	
Exposed Pad Width	E2	0.00	2.20	2.80
Overall Width	E		4.00 BSC	
Exposed Pad Length	D2	0.00	3.00	3.60
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

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